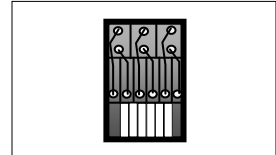
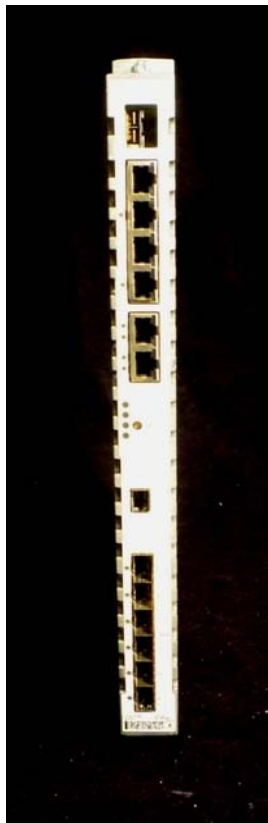


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**Ericsson GSM Baseband Unit  
KDU 137 569/1 R2B  
Model DUG20 01**

**January 2013**



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